

LISTING OF CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-25. (Cancelled).

Claim 26. (Currently amended) A process for producing a plurality of components, comprising the steps of:

joining a first surface of a substrate to a first surface of a carrier with a bonding force;

applying a protective layer;

machining the plurality of components out of the substrate;

releasing the bonding force between the carrier and the plurality of components with the application of UV light to the bonding force; [[and]]

detaching the plurality of components from the carrier in order to separate the plurality of components; and

removing the protective layer after the machining step and before the detaching step.

Claim 27. (Previously presented) The process as claimed in claim 26, wherein the plurality of components are separated from one another laterally during the machining step.

Claim 28. (Previously presented) The process as claimed in claim 26, wherein the substrate comprises glass or a vitreous material.

Claim 29. (Cancelled).

Claim 30. (Previously presented) The process as claimed in claim 26, wherein the step of machining comprises removing material from a second surface of the substrate, the second surface being on the opposite side of the substrate from the first surface, the material removed being at least as far as the first surface of the substrate.

Claim 31. (Previously presented) The process as claimed in claim 30, the step of machining further comprises removing a portion of material from the first surface of the carrier.

Claim 32. (Previously presented) The process as claimed in claim 26, wherein the step of machining comprises removing portions of the substrate and the carrier in succession until a position between the first surface and a second surface of the carrier is reached, the second surface being on the opposite side of the substrate from the first surface.

Claim 33. (Previously presented) The process as claimed in claim 26, wherein the step of machining comprises machining a multiplicity of laterally adjacent components out of the substrate in one working step.

Claim 34. (Previously presented) The process as claimed in claim 26, wherein the step of machining comprises vibratory lapping.

Claim 35. (Previously presented) The process as claimed in claim 34, wherein the vibratory lapping step comprises using a plurality of hollow lapping punches.

Claim 36. (Previously presented) The process as claimed in claim 35, wherein the plurality of hollow lapping punches have a cross section in the form of a continuous ring.

Claim 37. (Previously presented) The process as claimed in claim 26, wherein the step of machining comprises blasting with a blasting material.

Claim 38. (Previously presented) The process as claimed in claim 26, wherein the substrate has a second surface opposite the first surface, the second surface being a structured surface.

Claim 39. (Previously presented) The process as claimed in claim 26, wherein the detaching step comprises using a vacuum to separate the plurality of components from the carrier.

Claim 40. (Previously presented) The process as claimed in claim 26, further comprising applying a solder agent to at least a portion of a second surface of the substrate, the second surface of the substrate being on the opposite side of the substrate from the first surface.

Claim 41. (Previously presented) The process as claimed in claim 40, wherein the applying step comprises printing the solder agent on the portion of the second surface of the substrate in structured form as a solder-agent layer.

Claim 42. (Currently amended) The process as claimed in claim 40, ~~further comprising wherein the step of applying [[a]] the protective layer comprises applying the protective layer~~ to the second surface of the substrate and/or to the solder-agent layer.

Claim 43. (Cancelled)

Claim 44. (Previously presented) A process for producing a plurality of components, comprising the steps of:

- joining a carrier to a first surface of a substrate with a bonding force;
- applying a solder-agent layer to a second surface of the substrate, the second surface being on the opposite side of the substrate from the first surface;
- applying a protective layer to the second surface and to the solder-agent layer;
- machining the plurality of components out of the substrate by removing material all the way through the protective layer and the substrate and by removing material only

part way into the carrier;

removing the protective layer;

releasing the bonding force by the application of UV light; and

detaching the plurality of components from the carrier.

Claims 45-50. (Cancelled).